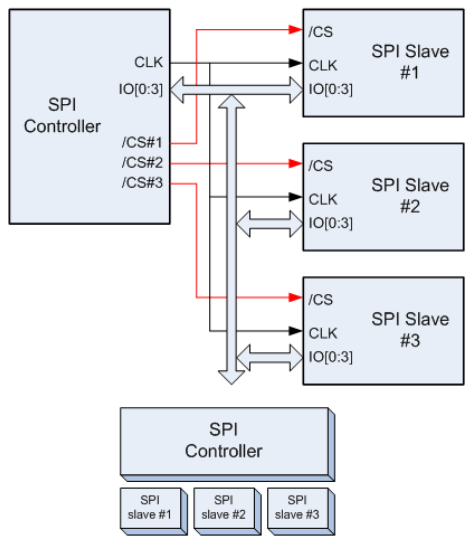
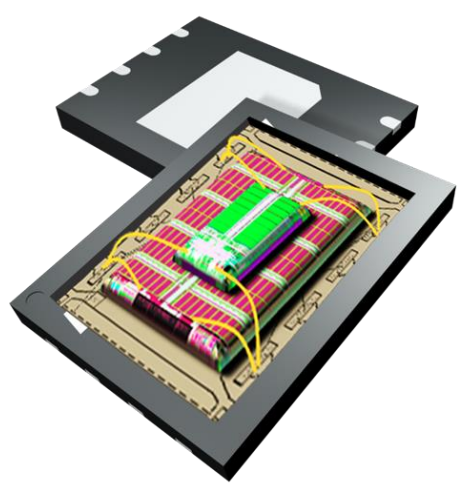
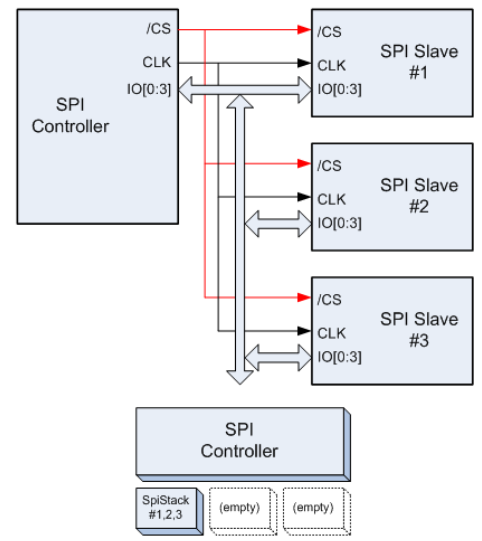


Winbond's W25M Series SpiStack®

Winbond is the first company to offer the new SpiStack® W25M Memory Series for “stacking” of homogeneous or heterogeneous flash, thus achieving memories of varying densities for code and data storage, while providing designers with flash solutions most appropriate for their design requirements. SpiStack architecture offers designers maximum flexibility in tailoring flash solutions to meet their specific memory-density and application requirements. The W25M Series provides a wide range of densities in the well-established 8-pin package to which designers are accustomed. W25M memories also feature the popular, multi-IO SpiFlash® interface featuring the popular Serial Peripheral Interface (SPI) and command set.



Current Solution



W25M SpiStack Solution

W25M SpiStack Family

- Stack flash dies to form a higher density part of choice
- User can select based on specific density requirement
- Serial Peripheral Interface (SPI)
- Backward compatible to existing SpiFlash

Homogeneous stacking – Two or more dies

- NOR dies for random access and high reliability
- NAND dies for large density and high write speed

Heterogeneous stacking – Two or more dies

- NOR and NAND dies stacked together

Concurrent Operation

- Read operation on one die + Write / Erase operation on another die
- Code execution not interrupted for data updates

Wide Range of Applications

- Mobile phones, Cameras, Printer, Servers, Set Top Box
Automotive, Bluetooth, GPS, Digital-TV, DSP, FPGA WLAN,
DSL/Cable Modem, Gateway, Industrial and more





Winbond SpiStack[®] Selection Guide

* Bold text = Sample available

S-NOR Density	S-NAND Density	Winbond Part # ²	Voltage	Package ³
16M-bit	512Mb	W25M165AVxIT	3V	x=(P, E, B, F ⁴)
	1Gb	W25M161AVxIT	3V	x=(E, B, F⁴)
	1Gb	W25M161AWxIT	1.8V	x=(E, B, F⁴)
32M-bit	512Mb	W25M325AVxIT	3V	x=(P, E, B, F ⁴)
	1Gb	W25M321AVxIT	3V	x=(E, B, F⁴)
	1Gb	W25M321AWxIT	1.8V	x=(E, B, F⁴)
64M-bit	512Mb	W25M645AVxIT	3V	x=(P, E, B, F ⁴)
	1Gb	W25M641AVxIT	3V	x=(E, B, F ⁴)
128M-bit	512Mb	W25M125AVxIT	3V	x=(P, E, B, F ⁴)
	1Gb	W25M121AVxIT	3V	x=(E, B, F⁴)
256M-bit	1Gb	W25M251AVxIT	3V	x=(E, B, F ⁴)
	1Gb	W25M251AWxIT	1.8V	x=(E, B, F ⁴)
512M-bit (2x256Mb)		W25M512JVxIQ	3V	x=(E, B, F⁴)
1Gb (2x512Mb)		W25Q01JVxxIQ	3V	x=(E, B, F ⁴)
	2Gb (2x1Gb)	W25M02GVxxIT	3V	xx=(ZE, TB, TC, SF⁴)
	2Gb (2x1Gb)	W25M02JWxxIT	1.8V	xx=(ZE, TB, TC, SF ⁴)

1. See data sheet for further technical information. This is subject to change without notice. 2. At the end of the part number, letter "T" represents "Green", Halogen Free and RoHS compliant packaging and Continuous Read mode as default (BUF=0); letter "Q" represents Green packaging and Quad Enabled as shipping default; letter "I" represents Industrial Temperature (-40°C to +85°C). 3 ZP or P=WSO8 6x5mm, ZE or E=WSO8 8x6mm, TB or B=TFBGA24 8X6mm (5X5 Matrix), SF or F=SO16 300mil. 4. Special Order.



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